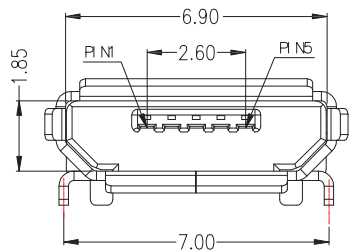
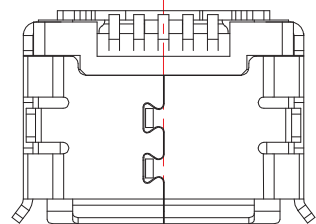
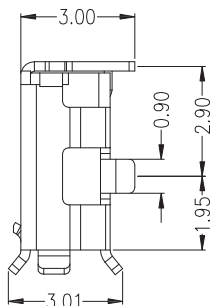
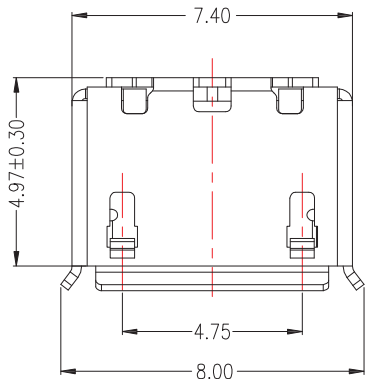
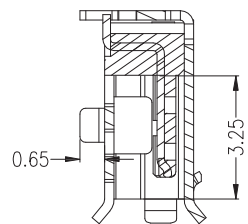


P.C.B LAYOUT MOUNTING PATTERN



NOTES:

- 1.MATERIAL:
 - 1.1 HOUSING: LCP,UL94V-0
 - 1.2 CONTACT: PHOSPHOR BRONZE
 - 1.3 SHELL: SUS
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 SHELL: NICKEL or TIN UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.8 A Max(PIN1,5)
1.0 A Max(PIN2,3,4)
- 3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

RoHS Compliant

TOLERANCES ARE

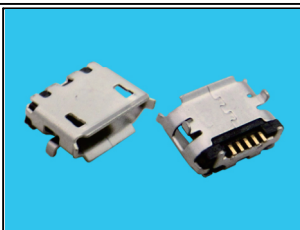


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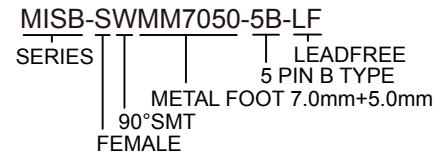
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DRAWING BY CY	
CHECKED BY GENIUS	
UNIT / mm	SCALE 1 : 1
DATE	
SIZE A4	PPOJECTION

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°



ORDER INFORMATION



DESCRIPTION: MICRO USB 5P SMT 牛角型後蓋 PH:7.0-5.0mm